

## SJ BIST™ for Mission-Critical Electronics

### Breakthrough in Interconnect Intermittent Fault Detection

### Preventing Impending IC- and Board-Level Failures

Intermittent and catastrophic faults in electronic control systems can now be prevented with Ridgetop Group's SJ BIST. The SJ BIST (Solder Joint Built-In Self-Test™) technology accurately detects and reports instances of high resistance, including intermittent opens, in cables, connectors and boards containing custom integrated circuits (ICs) and field-programmable gate arrays (FPGAs).

Solder joints, cables, connectors, and IC wire bonds are all subject to mechanical failure; they inevitably suffer damage from thermal and vibrational stresses, causing troublesome intermittent connections between components on the boards. In addition, internal IC structural elements in packages and substrates are also subject to similar failures from environmental

factors and improper handling. The ability to measure and detect interconnect degradation and predict the resultant failure of electronic modules is a true advancement in electronics reliability.

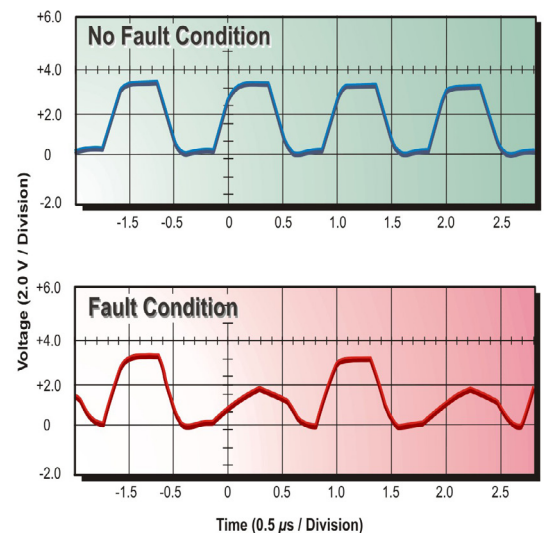
### Unique In-Situ Testing in Operating Circuits

Before SJ BIST, the only way to check active mission-critical circuitry for interconnection faults was to take them offline for testing and x-rays. These methods raise maintenance costs and often result in "no trouble found" or "could not duplicate" diagnoses. SJ BIST is installed in your operating components, and predicts when a component is likely to fail — with **zero false alarms**.

**Ridgetop's specialty?** Determining the extent of aging and degradation, and rooting out troublesome intermittencies.

As the world leader in electronic prognostics, Ridgetop Group provides a range of effective solutions for critical systems. These include award-winning, non-intrusive methods of determining state of health (SoH) and remaining useful life (RUL) for five levels of electronic system designs.

Our insertion tools and related libraries support implementations from the die-level, through package, board, module and system-level solutions.



**No-Fault and Fault Conditions  
in SJ BIST Two-Port Test;  
Fault Shows 150 Ω Resistance at 1 MHz**





## FEATURES AND BENEFITS

- Detects damage prior to catastrophic failure of FPGA
- Independently tested and verified
- Works with new processes and equipment
- Endorsed by leading automotive and aerospace customers

## Benefits

### Customized Built-In Self-Test Solutions

Starting with predesigned Intellectual Property (IP) blocks from the Sentinel Silicon™, InstaBIST™, and InstaCell™ libraries, Ridgetop customizes built-in self-testing to particular customer requirements.

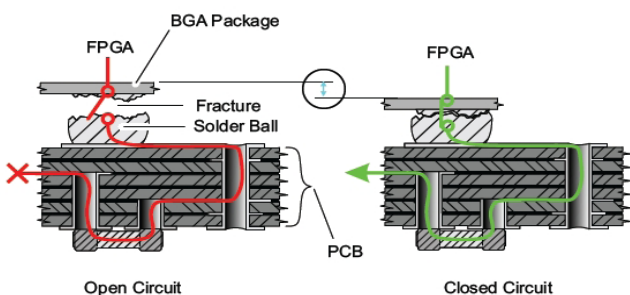
### Faults Detected in Operating Microcontroller Applications

SJ BIST replaces offline, full-functional testing and statistical degradation models with real-time, direct monitoring for FPGAs in the field. Its sensitivity is at least as low as 100 ohms, which compares favorably with a manufacturing reliability standard of 300 ohms.

### Proven, Definitive Results

SJ BIST has been independently validated on multiple FPGAs and ball grid array (BGA) packages, in multiple applications. It improves fault coverage without significantly increasing the complexity of the system.

### Intermittent Signal Failures



## Specific Effects

- Services provided by Ridgetop assure successful implementation
- Exceptional opportunities to reduce testing costs and improve product quality

- No downtime for testing
- Great savings in maintenance and inventory costs
- Minimal power requirement — for example, 150 mW to monitor eight pins
- Fast test time

- Provided as an IP core, incorporated into existing self-test backbone
- Supports condition-based maintenance (CBM)
- Detects damage prior to catastrophic failure of FPGA

Intermittent signal failures are caused by solder ball fractures that periodically open and shut, as shown at left.

Vibration, motion, thermal, and other stresses cause conditions where a solder ball can move enough to open or shut a fracture.

